REVISION HISTORY Notes - Unless otherwise noted DESCRIPTION DATE ENG REV 1. Resistances values in Ohms 2. Capacitance values in microfarads (uF) 04-08-2011 Α1 INITIAL SCHEMATIC AIY 3. All 0.1uF and 0.01uF capactors are decoupling and should be placed near the IC they are shown with. A2 REMOVED ANALOG SWITCHES 05-12-2011 AKS CHANGED FEEDBACK CHANGED THE SIZE OF THE SENSE RESITORS 05-25-2011 A3 AKS ADDED PULL-UP/PULL-DOWN ON SPI LINES REMOVED 0-OHM RESISTORS ON CURRENT SENSE В1 FIXED DRV8301 CURRENT SENSE POLARITY NO-POP ALL EXTERNAL CURRENT SENSE COMPONENTS 07-14-2011 JPW CHANGED C14 TO 25V 0805 PACKAGE FETS CHANGED TO VISHAY SUM110N06-3M9H CHANGED CURRENT SENSE RESISTORS TO 2mOHM RECONFIGURED DC BUS CAPS SPLIT POWER CONNECTOR INTO TWO CONNECTORS C1 LAYOUT CHANGES TO IMPROVE GROUND CONNECTIONS FOR 08-12-2011 AKS DE-COUPLING CAPACITORS C10, C14, C72 CREATED BOM VARIANT FOR DRV8302 CHANGED R12, R13, R21 TO 1K CHANGED R43, R47 TO 1K (DRV8302 ONLY) POPULATED EXTERNAL GAIN OP-AMPS AND CHANGED 01-18-2012 D1 CONNECTIONS FOR THESE TO DAUGHTER CARD

Page 1 - Title - Index - Revisions

Page 2 - Block Diagram

Page 3 - DRV8301/DRV8302

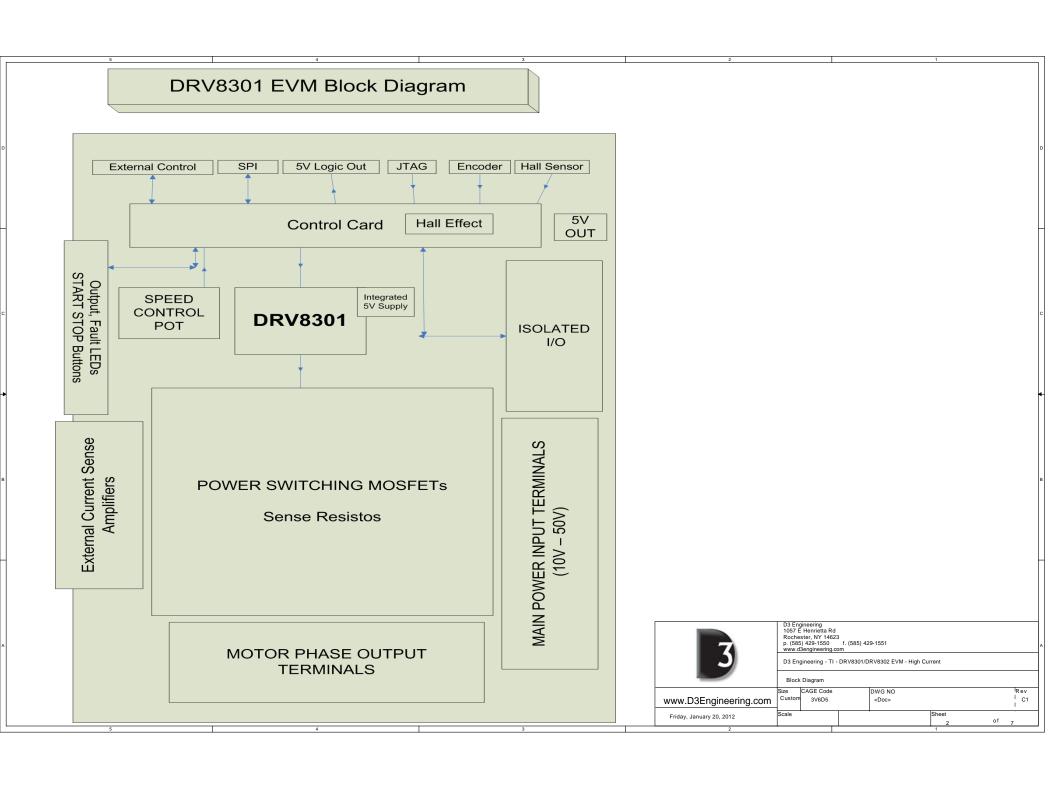
Page 4 - Isolation Circuitry

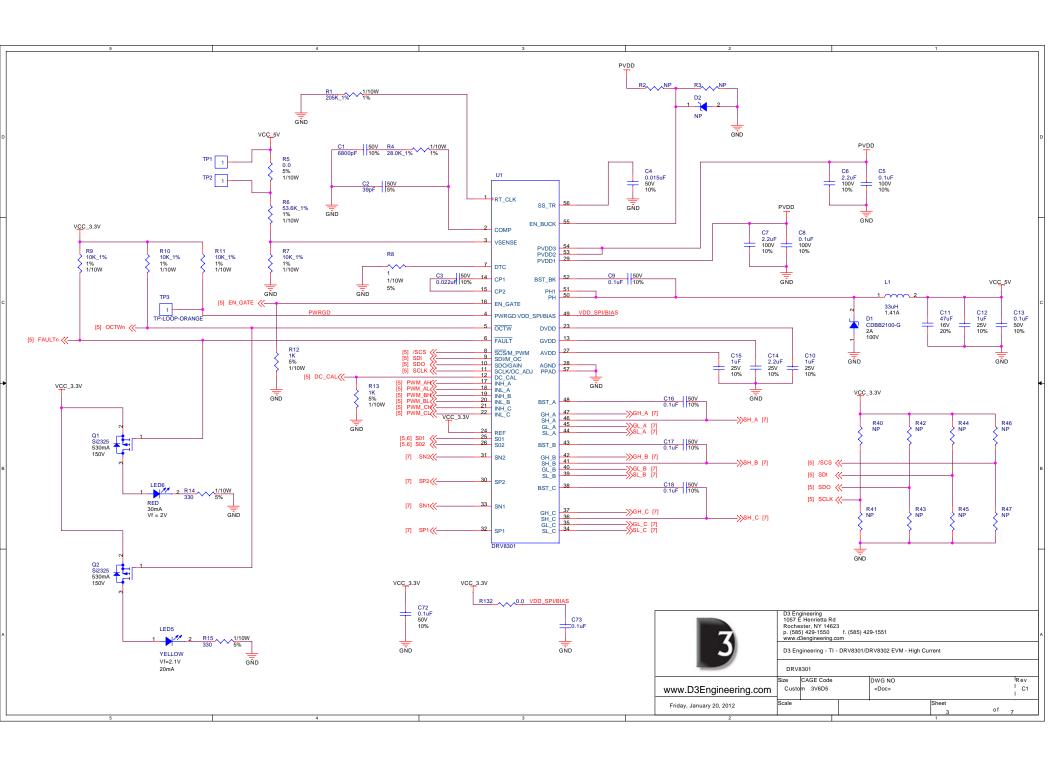
Page 5 - DIMM Socket - Connectors - Switches

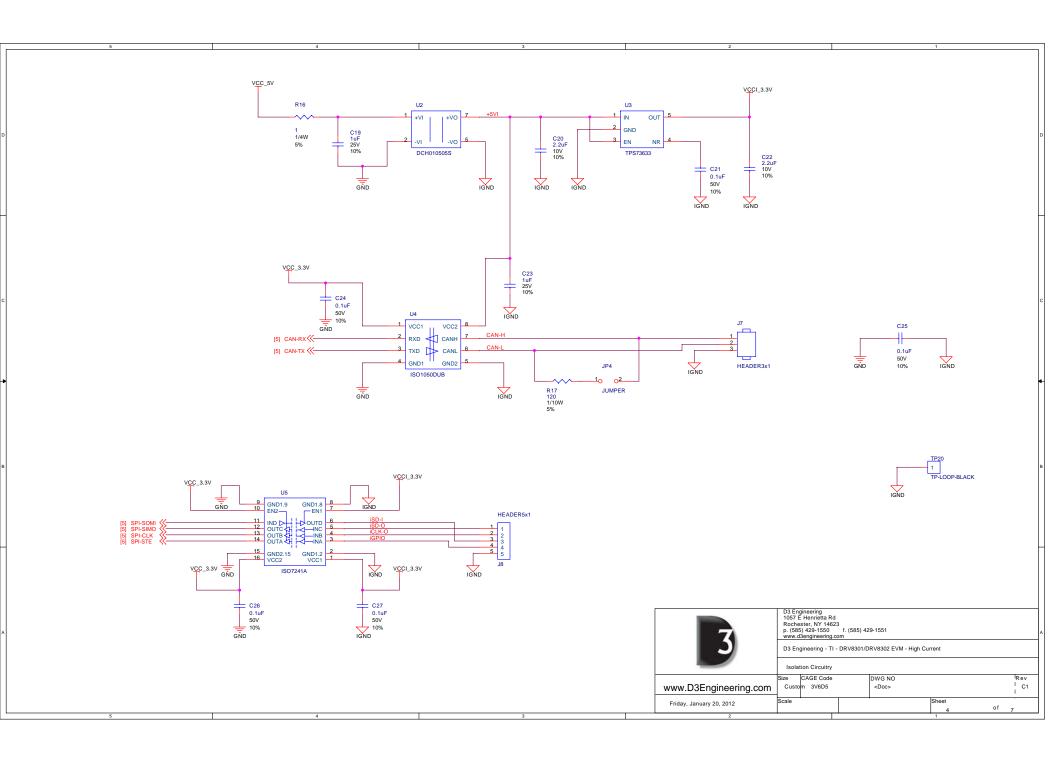
Page 6 - Power Input - Voltage Regulators - Current Sense Amplifiers

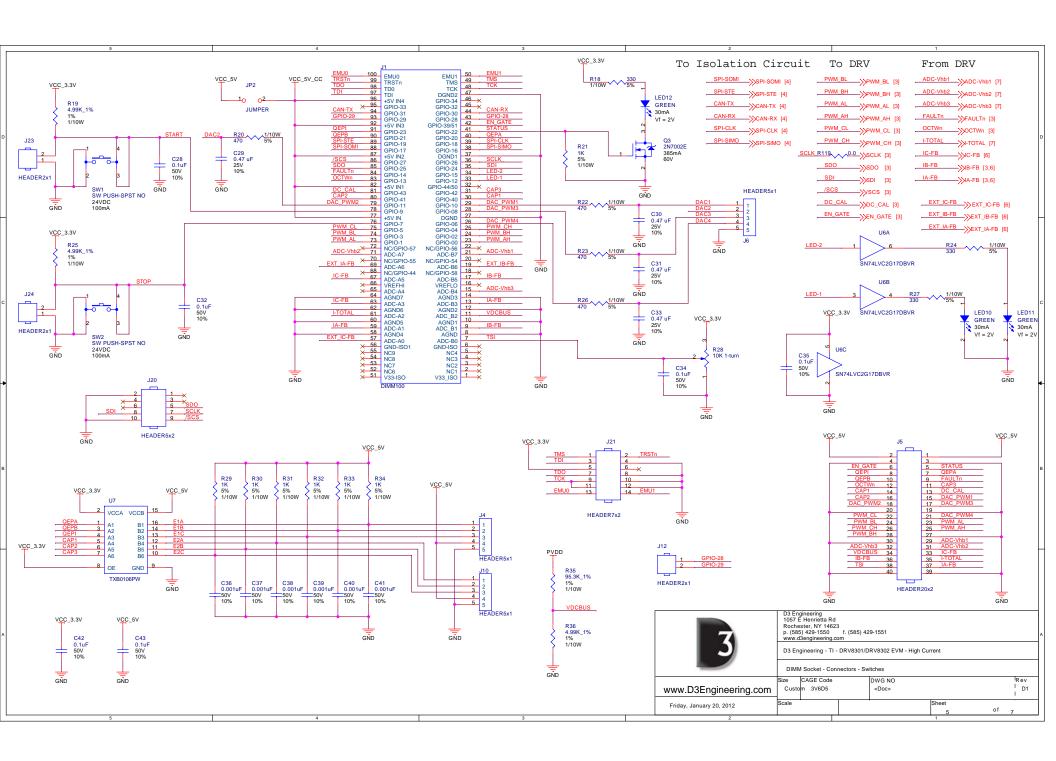
Page 7 - Half Bridges - Motor Output

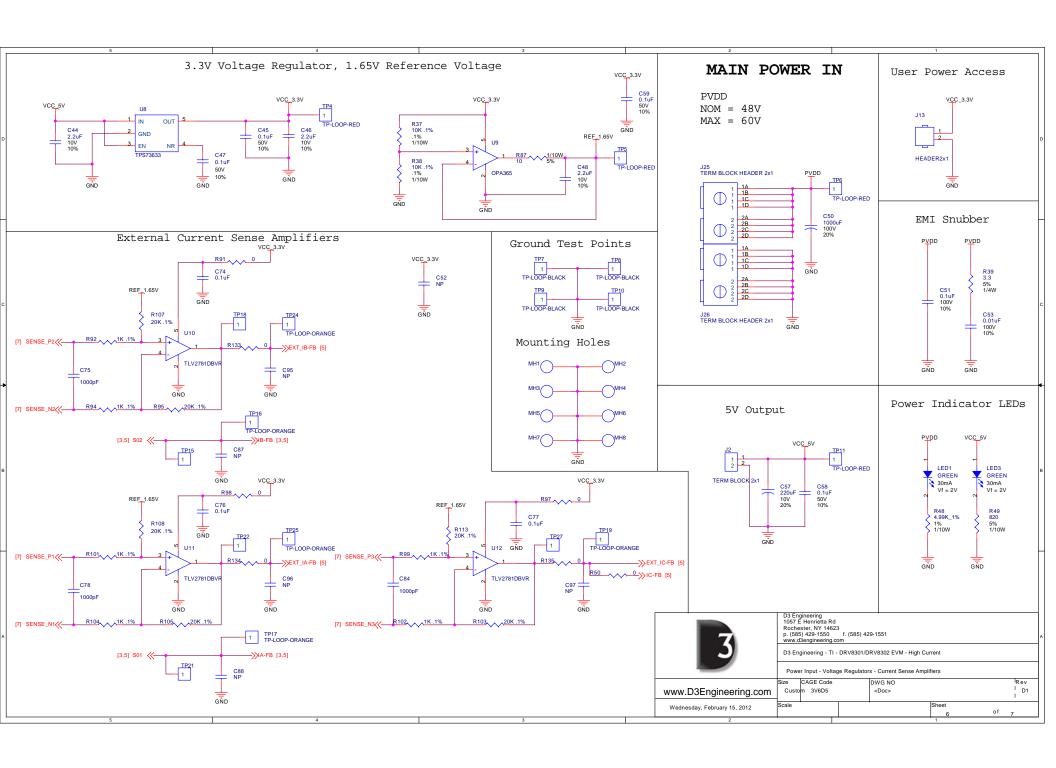
3	D3 Engineering 1057 E Henrietta Rd Rochester, NY 14623 p. (585) 429-1550 www.d3engineering.com D3 Engineering - TI - DRV8301/DRV8302 EVM - High Current							А
www.D3Engineering.com		- Index - Revis CAGE Code 3V6D5	ions	DWG NO <doc></doc>			Rev I D1	
Friday, January 20, 2012	Scale		Sheet 1		Sheet 1	of	7	

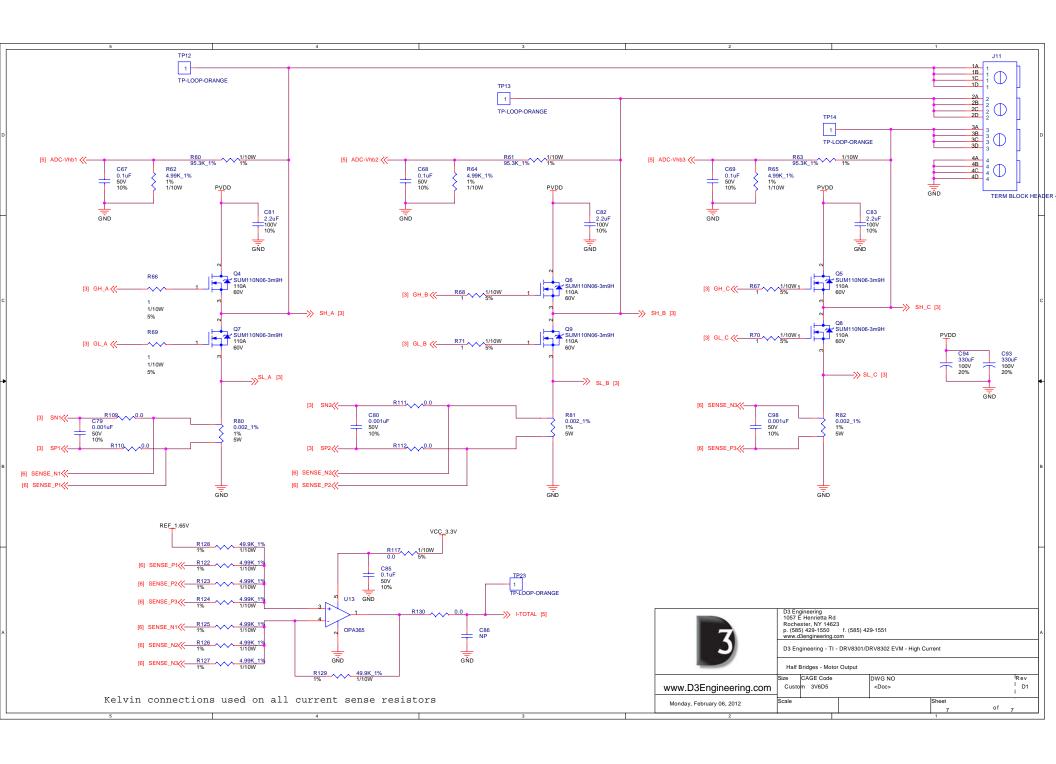












IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom Amplifiers amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com/omap

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>